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(54) Title: **ORGANOSILICATE RESIN FORMULATION FOR USE IN MICROELECTRONIC DEVICES**

(57) Abstract: A curable organosilicate composition that is employed to form one or more layers in the fabrication of electronic devices comprising: (a) an alkoxy or acyloxy silane having at least one group containing ethylenic unsaturation which group is bonded to the silicon atom (b) an alkoxy oracyloxy silane having at least one group containing an aromatic ring which group is bonded to the silicon atom, (c) a latent acid catalyst, and (d) optionally an alkoxy or acyloxy silane having at least one C<sub>1</sub>-C<sub>6</sub> alkyl group bonded to the silicon atom.

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